



**THE DATASHEET OF  
PI6C5921512ZDIEX**



**PI6C5921512**

**12 Output LVDS Fanout Buffer**

**Features**

- 12 Differential LVDS outputs
- 2 Selectable reference inputs support either single-ended or differential
- Up to 1.5GHz output frequency
- Ultra low additive phase jitter: < 0.01 ps (typ) (differential 156.25MHz, 12KHz to 20MHz integration range)
- Low skew between outputs
- Low delay from input to output
- Separate Input output supply voltage for level shifting
- 2.5V / 3.3V power supply
- Industrial temperature support
- TQFN-40 package

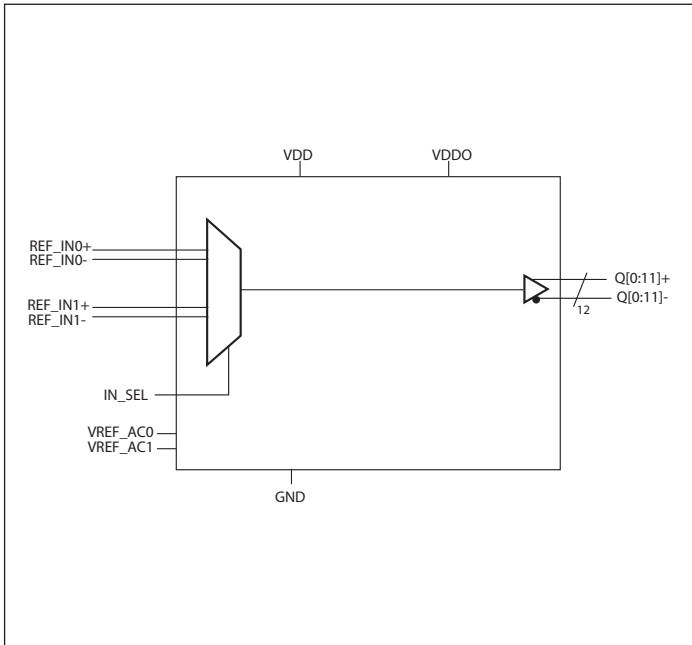
**Description**

The PI6C5921512 is a high performance LVDS fanout buffer device which supports up to 1.5GHz frequency. This device is ideal for systems that need to distribute low jitter LVDS clock signals to multiple destinations.

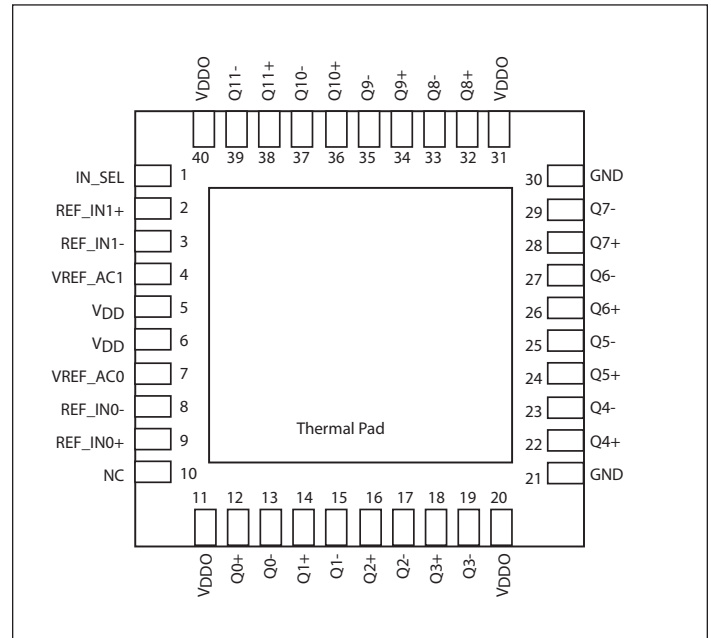
**Applications**

- Networking systems including switches and Routers
- High frequency backplane based computing and telecom platforms

**Block Diagram**



**Pin Configuration (40-Pin TQFN)**



## Pin Description

Pin #	Pin Name	Type		Description
1	IN_SEL	Input	Pulldown	Input clock select. See Table 1 for function. LVCMOS/LVTTL interface levels.
2,3	REF_IN1+	Input		Reference input 1. Accepts Differential or Single Ended inputs
	REF_IN1-			
4	VREF_AC1	Output		Bias voltage output for REF_IN1
5, 6	VDD	Power		Core power supply
7	VREF_AC0	Output		Bias voltage output for REF_IN0
8, 9	REF_IN0-	Input		Reference input 0. Accepts Differential or Single Ended inputs
	REF_IN0+			
10	NC	-		No Connect
11, 20, 31, 40	VDDO	Power		Output power supply
12, 13	Q0+	Output		LVDS output pair 0.
	Q0-			
14, 15	Q1+	Output		LVDS output pair 1.
	Q1-			
16, 17	Q2+	Output		LVDS output pair 2.
	Q2-			
18, 19	Q3+	Output		LVDS output pair 3.
	Q3-			
21, 30	GND	Power		Power supply ground
22, 23	Q4+	Output		LVDS output pair 4.
	Q4-			
24, 25	Q5+	Output		LVDS output pair 5.
	Q5-			
26, 27	Q6+	Output		LVDS output pair 6.
	Q6-			
28, 29	Q7+	Output		LVDS output pair 7.
	Q7-			
32, 33	Q8+	Output		LVDS output pair 8.
	Q8-			
34, 35	Q9+	Output		LVDS output pair 9.
	Q9-			
36, 37	Q10+	Output		LVDS output pair 10.
	Q10-			

### Pin Description Cont.

Pin #	Pin Name	Type	Description
38, 39	Q11+	Output	LVDS output pair 11.
	Q11-		
Thermal pad	-	-	Thermal pad. Connect to ground.

### Function Table

Table 1: Input select function

IN_SEL	Function
0	REF_IN0 is the selected reference input
1	REF_IN1 is the selected reference input
Open	No inputs selected. Outputs Hi-Z

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$C_{IN}$	Input Capacitance			2		pF
$R_{PULLDOWN}$	Input Pulldown Resistor			200		k $\Omega$
$R_{PULLUP}$	Input Pullup Resistor			200		k $\Omega$

**Maximum Ratings** (Above which the useful life may be impaired. For user guidelines, not tested)

Storage temperature.....	-55 to +150°C
Supply Voltage to Ground Potential ( $V_{DD}, V_{DDO}$ )...	-0.5 to +4.6V
Inputs (Referenced to GND) .....	-0.5 to $V_{DD}+0.5V$
Clock Output (Referenced to GND).....	-0.5 to $V_{DD}+0.5V$
Latch up.....	200mA
ESD Protection (Input) .....	2000 V min (HBM)
ESD Protection (Input) .....	1000 V min (CDM)

**Note:**  
Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**Power Supply Characteristics and Operating Conditions**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
$V_{DD}$	Core Supply Voltage		3.135	3.3	3.465	V
			2.375	2.5	2.625	V
$V_{DDO}$	Output Supply Voltage		3.135	3.3	3.465	V
			2.375	2.5	2.625	V
$I_{DD}$	Core Power Supply Current			120	213	mA
$I_{DDO}$	Output Power Supply Current	All LVDS outputs loaded				
$T_A$	Ambient Operating Temperature		-40		85	°C

**DC Electrical Specifications - Differential Inputs**

Symbol	Parameter		Min.	Typ.	Max.	Units
$I_{IH}$	Input High current	Input = $V_{DD}$			20	uA
$I_{IL}$	Input Low current	Input = GND	-20			uA
$V_{IH}$	Input high voltage				$V_{DD}+0.3$	V
$V_{IL}$	Input low voltage		-0.3			V
$V_{ID}$	Input Differential Amplitude PK-PK		0.1			V
$V_{CM}$	Common mode input voltage		GND + 0.5		$V_{DD}-0.85$	V
$ISO_{MUX}$	MUX isolation			-89		dBc

### DC Electrical Specifications - LVCMOS Inputs

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$I_{IH}$	Input High current	Input = $V_{DD}$			150	$\mu A$
$I_{IL}$	Input Low current	Input = GND	-150			$\mu A$
$V_{IH}$	Input high voltage	$V_{DD}=3.3V$	2.0		$V_{DD}+0.3$	V
		$V_{DD}=2.5V$	1.7		$V_{DD}+0.3$	V
$V_{IL}$	Input low voltage	$V_{DD}=3.3V$	-0.3		0.8	V
		$V_{DD}=2.5V$	-0.3		0.7	V

### DC Electrical Specifications- LVDS Outputs

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
$V_{OH}$	Output High voltage			1.4		V
$V_{OL}$	Output Low voltage			1.0		V
$V_{OD}$	Differential output voltage	@800MHz to $\leq 1.5GHz$	200		400	mV
		@ $\leq 800MHz$	250		450	mV
$DV_{OD}$	Change in $V_{OD}$ between completely output states		-50		50	mV
$V_{ocm}$	Output commode voltage			1.25		V
$DV_{ocm}$	Change in $V_{ocm}$ between completely output states				50	mV

### AC Electrical Specifications – Differential Inputs

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
$F_{IN}$	Clock input frequency				1500	MHz
$V_{INPP}$	Differential Input peak to peak voltage	$1.5GHz \leq F_{IN} \leq 2 GHz$	0.2		1.5	V
		$F_{IN} \leq 1.5 GHz$	0.1		1.5	V
ER	Input Edge Rate		1.5			V/ns

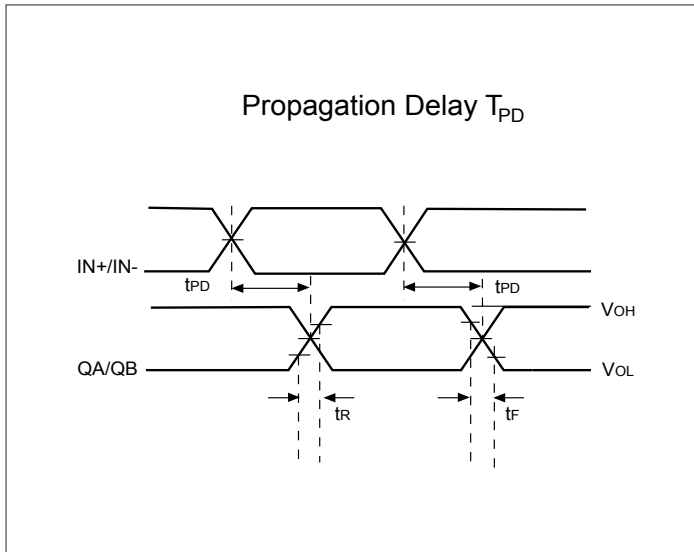
### AC Electrical Specifications – LVCMOS Inputs

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
F <sub>IN</sub>	Clock input frequency				200	MHz
ER	Input Edge Rate		1.5			V/ns

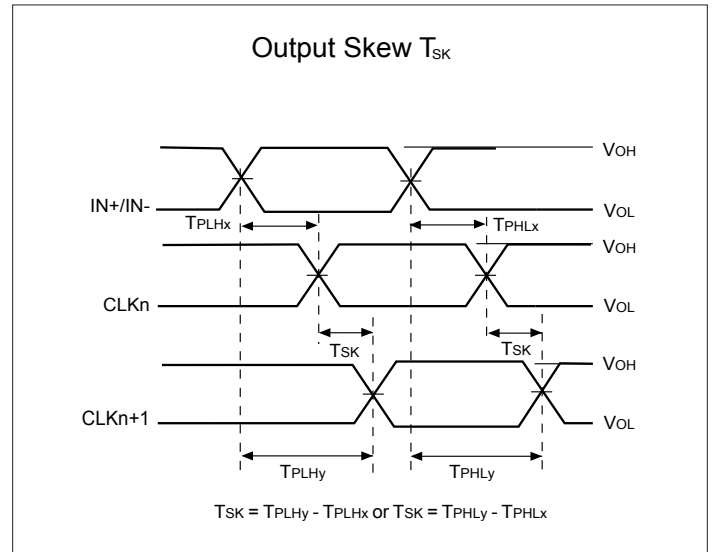
### AC Electrical Specifications – LVDS Outputs

Parameter	Description	Conditions	Min.	Typ.	Max.	Units
F <sub>OUT</sub>	Clock output frequency	LVDS			1500	MHz
T <sub>r</sub>	Output rise time	From 20% to 80%		150		ps
T <sub>f</sub>	Output fall time	From 80% to 20%		150		ps
T <sub>ODC</sub>	Output duty cycle	<1.5GHz	48		52	%
T <sub>j</sub>	Buffer additive jitter RMS	156.25MHz, 12kHz to 20MHz		0.01		ps
		156.25MHz, 10kHz to 1MHz		0.01		ps
T <sub>SK</sub>	Output Skew			13	30	ps
T <sub>PD</sub>	Propagation Delay			620	700	ps
T <sub>OD</sub>	Valid to HiZ				100	ns
T <sub>OE</sub>	HiZ to valid				100	ns
T <sub>P2P Skew</sub>	Part to Part Skew <sup>1</sup>		-50		50	ps
V <sub>REF_AC</sub>	Input bias voltage	I <sub>AC</sub> = 2mA		1.25		V

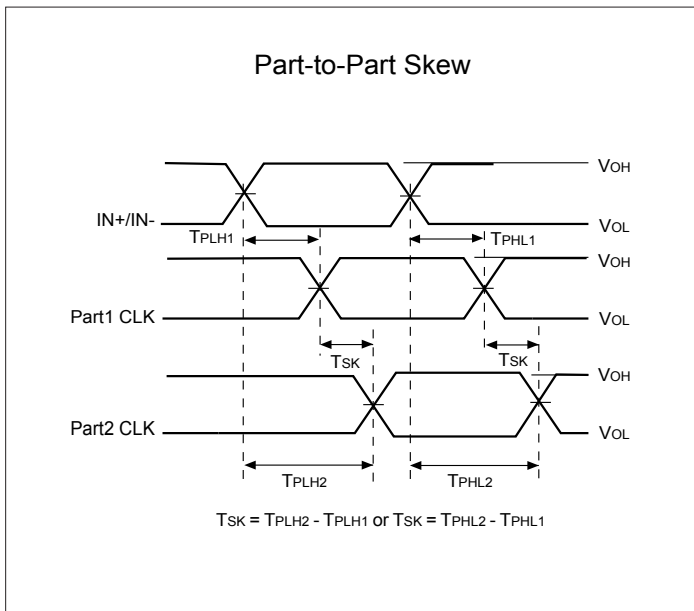
**Propagation Delay**



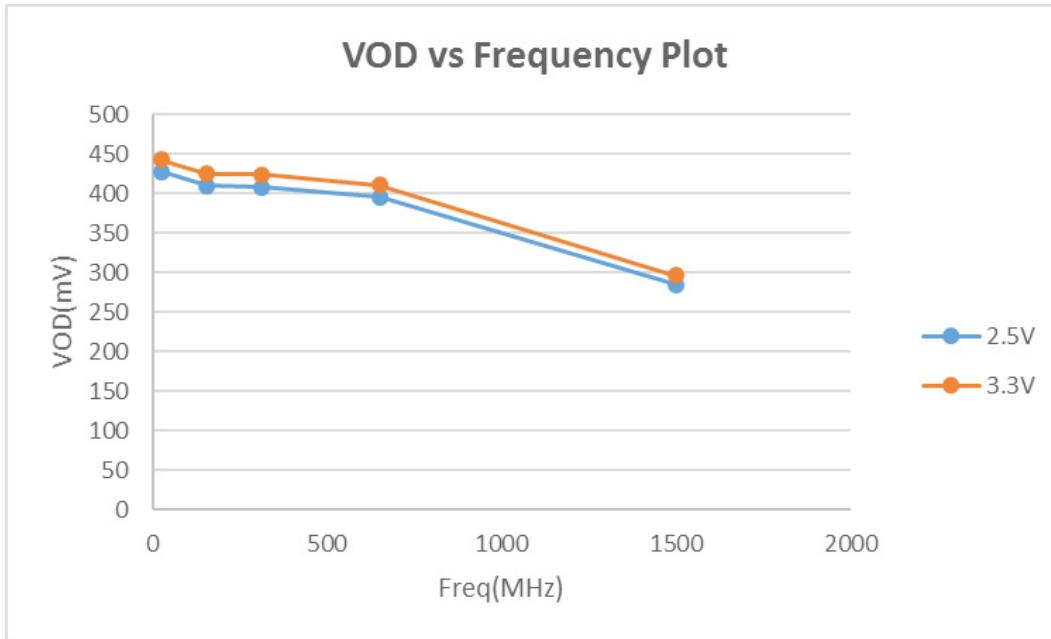
**Output Skew**



**Part to Part Skew**

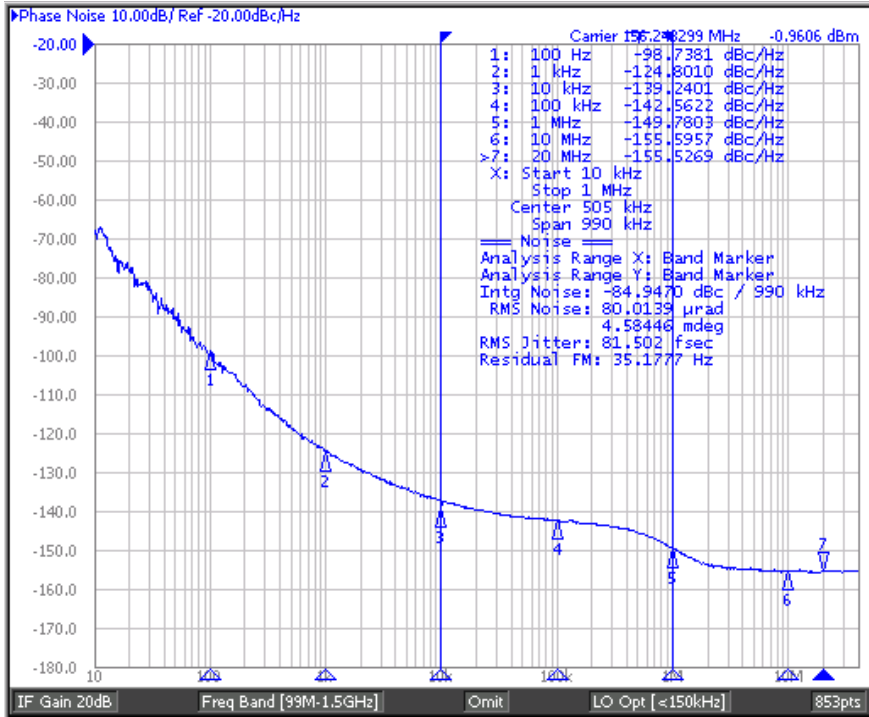


### LVDS Output Swing vs. Frequency

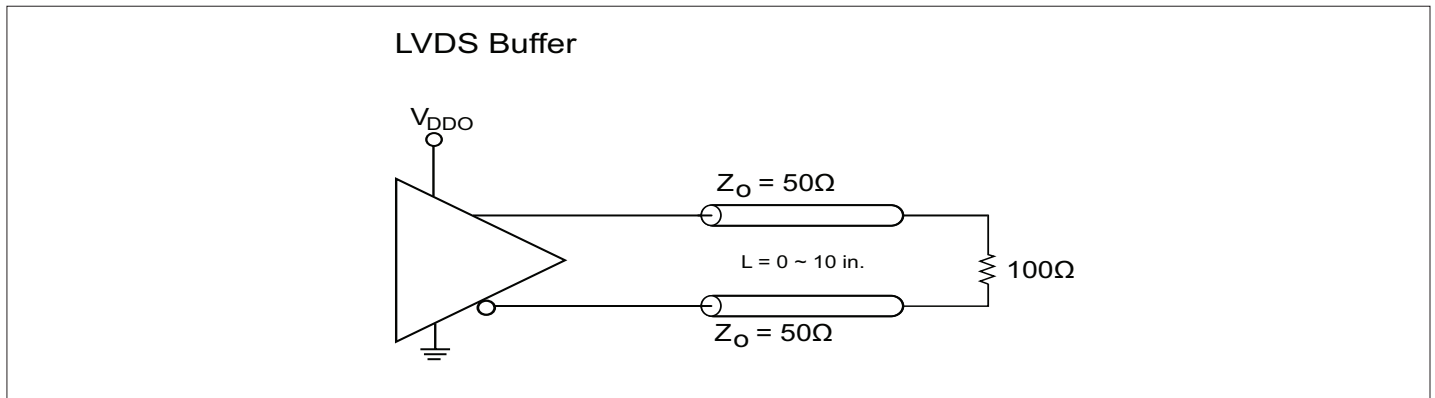


### Phase Noise and Additive Jitter

$$\text{Additive jitter} = \sqrt{(\text{Output jitter}^2 - \text{Input jitter}^2)}$$



### Configuration Test Load Board Termination for LVDS/ LVDS Outputs



## Application Information

### Wiring the differential input to accept single ended levels

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_{REF} = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio of R1 and R2 might need to be adjusted to position the  $V_{REF}$  in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{DD} = 3.3V$ ,  $V_{REF}$  should be 1.25V and  $R1/R2 = 0.609$ .

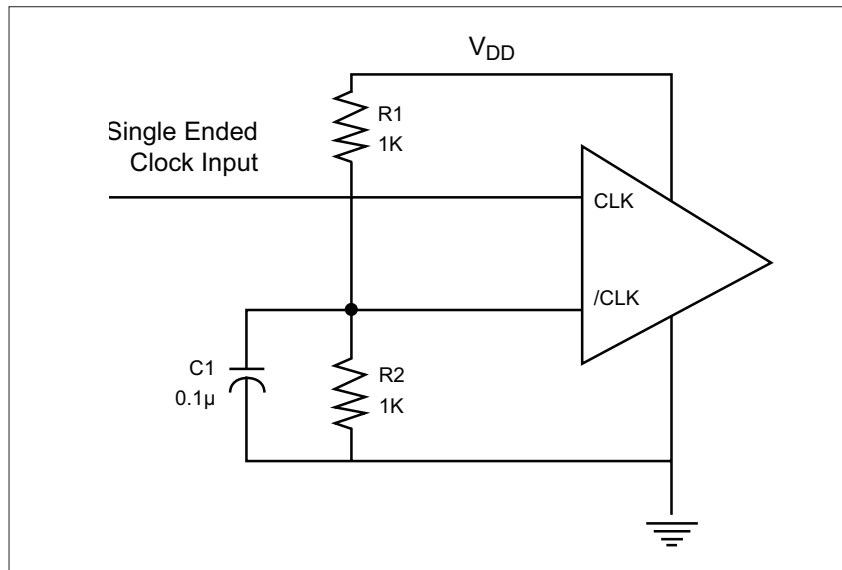
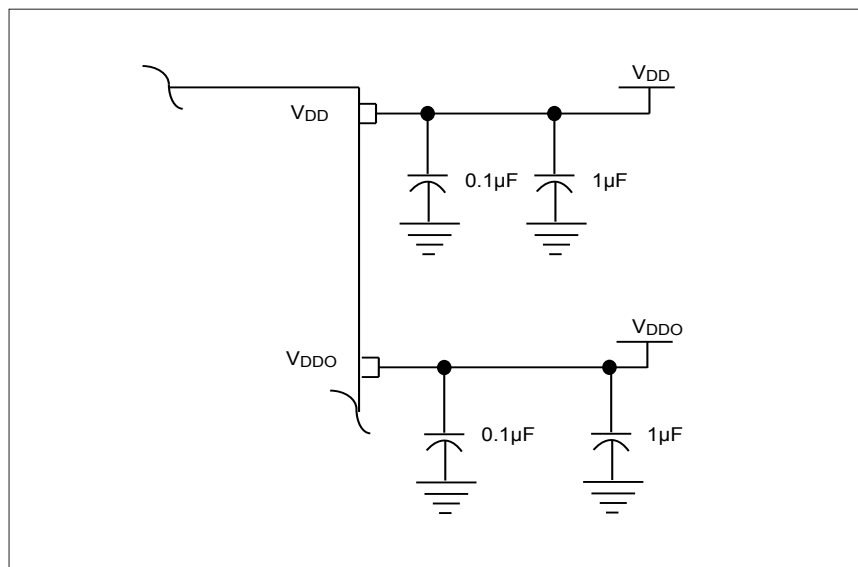


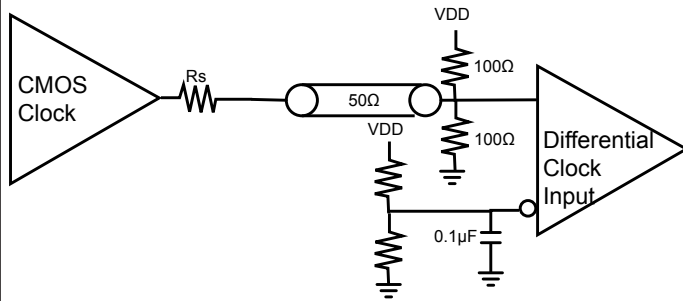
Figure 1. Single-ended input to Differential input device

## Power Supply Filtering Techniques

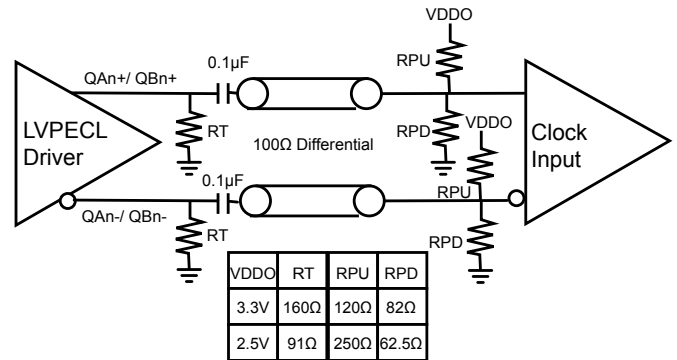
As in any high speed analog circuitry, the power supply pins are vulnerable to random noise. To achieve optimum jitter performance, power supply isolation is required. All power pins should be individually connected to the power supply plane through vias, and 0.1µF and 1µF bypass capacitors should be used for each pin.



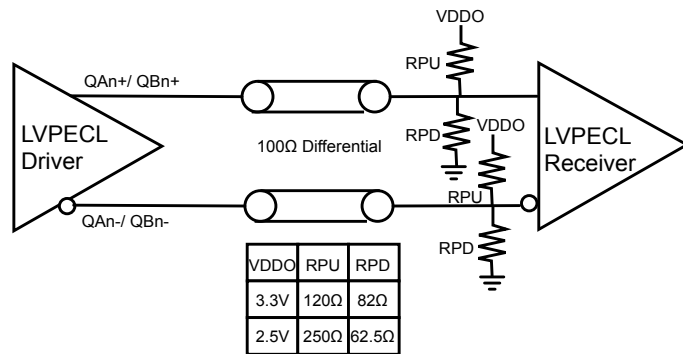
**Single Ended Input, DC couple**



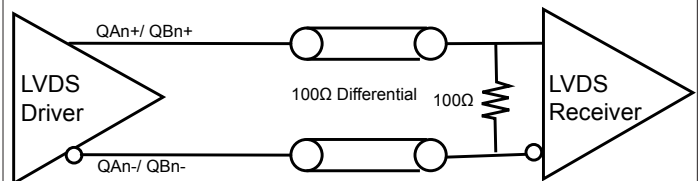
**LVDS, AC Couple, Thevenin Equivalent**



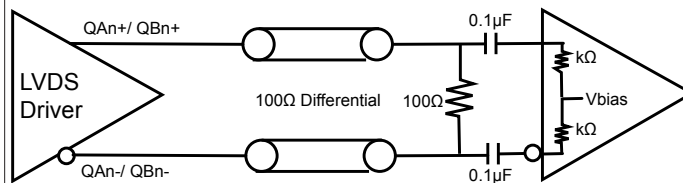
**LVDS, DC Couple, Thevenin Equivalent**



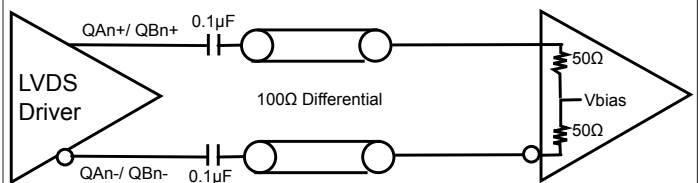
**LVDS DC Couple**

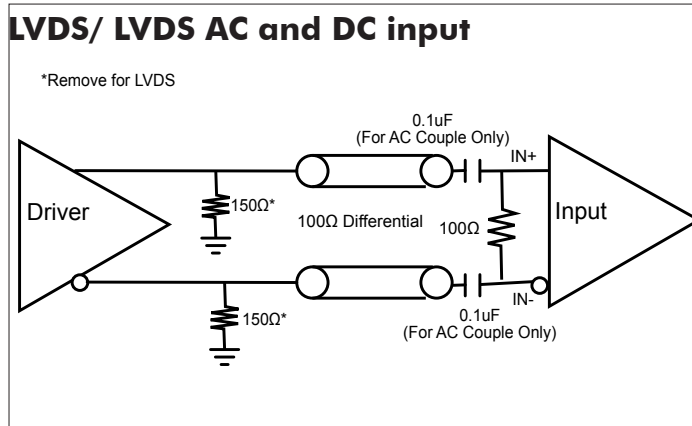


**LVDS AC Couple at Load**



**LVDS AC Couple with Internal Termination**





### Thermal Information

Symbol	Description	Condition	
$\Theta_{JA}$	Junction-to-ambient thermal resistance	Still air	26.18 °C/W
$\Theta_{JC}$	Junction-to-case thermal resistance		10.52 °C/W

### Part Marking

Top mark not available at this time. To obtain advance information regarding the top mark, please contact your local sales representative.

PI6C5921512

**Packaging Mechanical: 40-TQFN (ZD)**

SYMBOLS	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.203 REF.		
b	0.18	0.25	0.30
D	5.90	6.00	6.10
E	5.90	6.00	6.10
e	0.50 BSC		
L	0.35	0.40	0.45
D2	4.40	4.50	4.55
E2	4.40	4.50	4.55

**Notes:**  
 1. All dimensions are in mm.  
 2. Refer JEDEC MO-220.  
 3. Bilateral coplanarity zone applies to the exposed heat sink slug as well as the terminals.

**PERICOM**  
Enabling Serial Connectivity

DATE: 07/12/11

DESCRIPTION: 40-contact, Thin Fine Pitch Quad Flat No-Lead, TQFN

PACKAGE CODE: ZD (ZD40)

DOCUMENT CONTROL #: PD-2021

REVISION: C

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please check: <http://www.diodes.com/design/support/packaging/pericom-packaging/packaging-mechanicals-and-thermal-characteristics/>

**Ordering Information**

Ordering Code	Package Code	Package Type	Operating Temperature
PI6C5921512ZDIEX	ZD	40-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN)	-40 °C to 85 °C

**Notes:**

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
2. See <http://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free. Thermal characteristics can be found on the company web site at [www.diodes.com/design/support/packaging/](http://www.diodes.com/design/support/packaging/)
3. E = Pb-free and Green
4. X suffix = Tape/Reel

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